



VMDSEMI

**VUSB1P2R280PA**

**Datasheet**



VMDSEMI

**28mΩ, -12V, P-Channel Power MOSFET**
**VUSB1P2R280PA**
**General Description**
**Symbol**

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
-12V	28mΩ@-4.5V	-6A
	32mΩ@-3.7V	
	40mΩ@-2.5V	
	63mΩ@-1.8V	
	150mΩ@-1.5V	

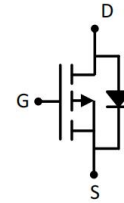


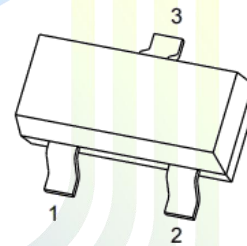
Figure 1 Symbol of VUSB1P2R280PA

**Features**

- Trench FET Power MOSFET
- Excellent  $R_{DS(on)}$  and Low Gate Charge

**Application**

- DC/DC Converter
- Load Switch for Portable Devices
- Battery Switch

**Package Type**


1. GATE
2. SOURCE
3. DRAIN

**SOT-23**

Figure 2 Package Type of VUSB1P2R280PA

**Ordering Information**

Product Name	Package
VUSB1P2R280PA	SOT-23

**Absolute Maximum Ratings** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	-12	V
Gate-Source Voltage	$V_{GSS}$	$\pm 8$	V
Continuous Drain Current <sup>Note1</sup>	$I_D$	-6	A
Pulsed Drain Current <sup>Note2</sup>	$I_{DM}$	-20	
Total Power Dissipation <sup>Note4</sup>	$P_D$	0.35	W
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient <sup>Note5</sup>	$R_{\theta JA}$		357		$^\circ\text{C/W}$



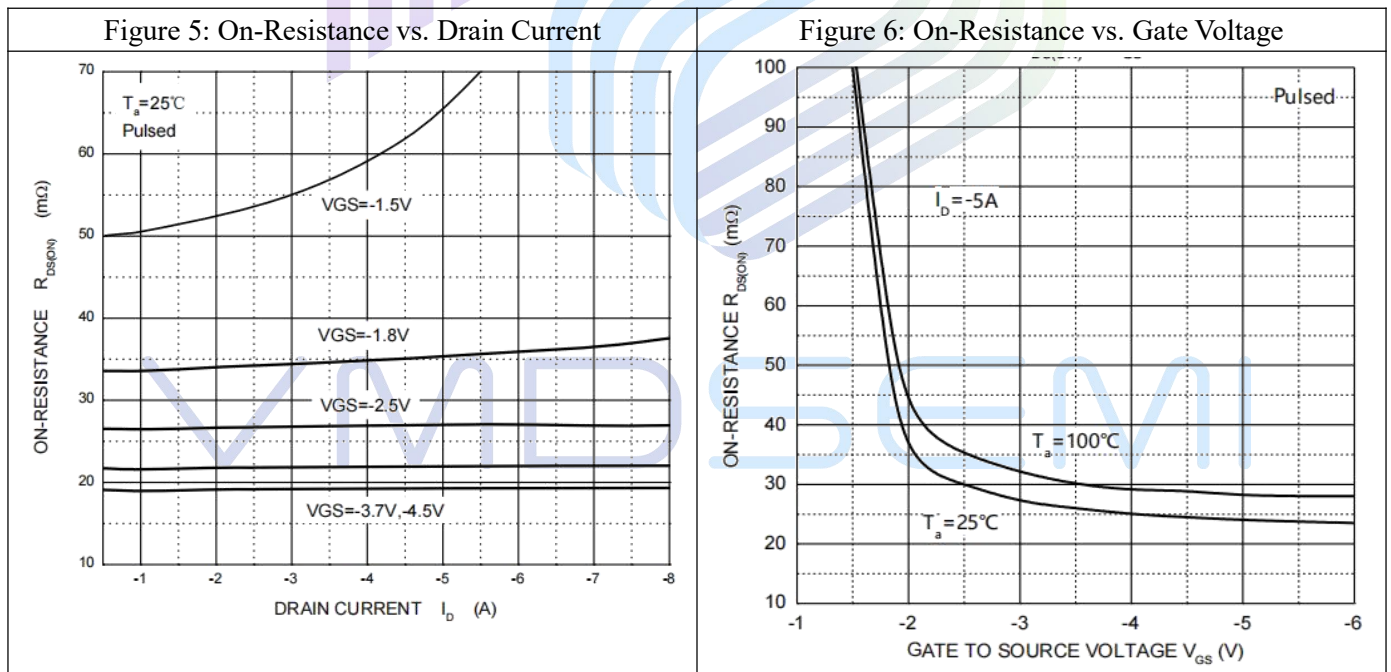
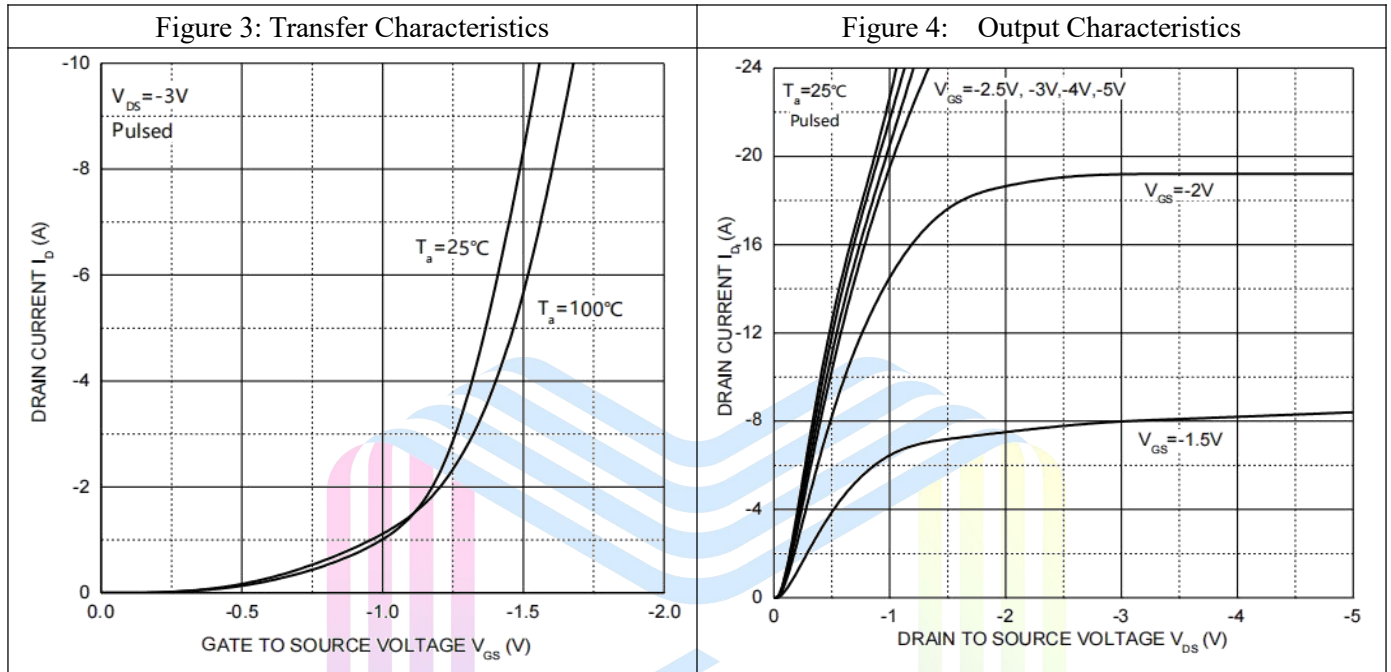
**Electrical Characteristics** ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

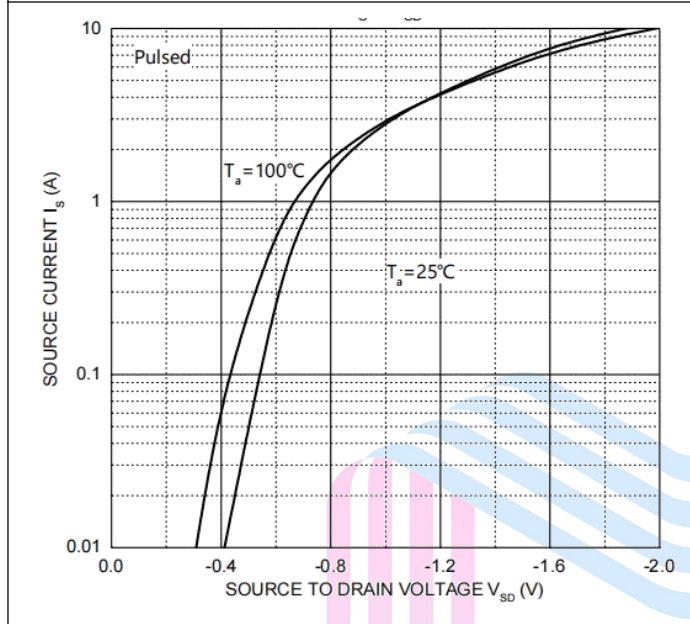
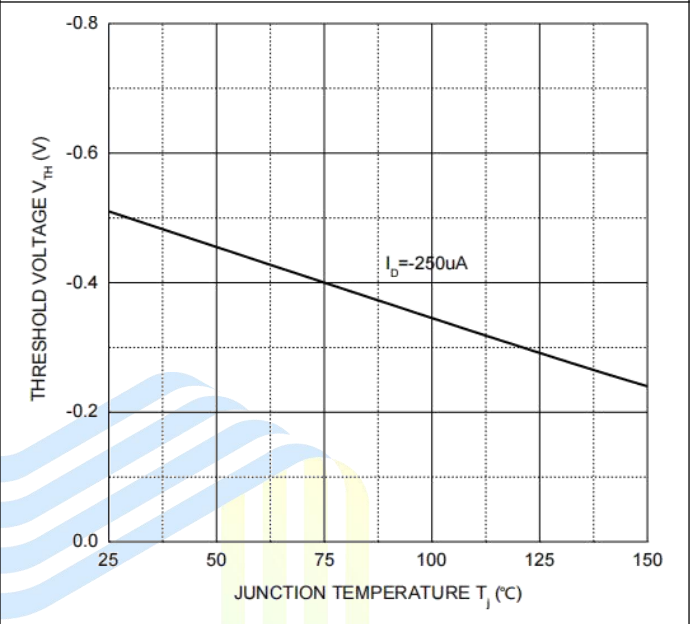
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	-12			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-12V, V_{GS}=0V$			-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 8V, V_{DS}=0V$			$\pm 100$	nA
Gate Threshold Voltage <sup>Note3</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.65	-1	V
Static Drain-Source On-Resistance <sup>Note3</sup>	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-5A$		19	28	mΩ
		$V_{GS}=-3.7V, I_D=-4.6A$		21	32	
		$V_{GS}=-2.5V, I_D=-4.3A$		27	40	
		$V_{GS}=-1.8V, I_D=-1A$		35	63	
		$V_{GS}=-1.5V, I_D=-0.5A$		50	150	
Forward Transconductance <sup>Note3</sup>	$g_{FS}$	$V_{DS}=-5V, I_D=-5A$		18		S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=-6V$		1275		pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$		255		pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$		236		pF
Total Gate Charge	$Q_g$	$V_{DS}=-6V$		14	21	nC
Gate-Source Charge	$Q_{gs}$	$V_{GS}=-4.5V$		2.3		
Gate-Drain Charge	$Q_{gd}$	$I_D=-5A$		3.6		
Gate Resistance	$R_g$	$f=1MHz, \text{Open drain}$	1.9		19	Ω
<b>Switching Parameters</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-6V$		26	40	ns
Turn-on Rise Time	$t_r$	$V_{GS}=-4.5V$		24	40	
Turn-off Delay Time	$t_{d(off)}$	$R_L=6\Omega$		45	75	
Turn-off Fall Time	$t_f$	$R_G=1\Omega, I_D=-4A$		20	35	
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>Note3</sup>	$V_{DS}$	$V_{GS}=0V, I_S=-4A$			-1.2	V
Continuous Source Current	$I_S$	$T_C=25\text{ }^\circ\text{C}$			-1.4	A
Pulsed Source Current	$I_{SM}$				-20	
Diode Reverse Recovery Time	$t_{rr}$	$I_F=-4A$			48	ns
Diode Reverse Recovery Charge	$Q_{rr}$	$dI/dt=100A/\mu s$			16	nC

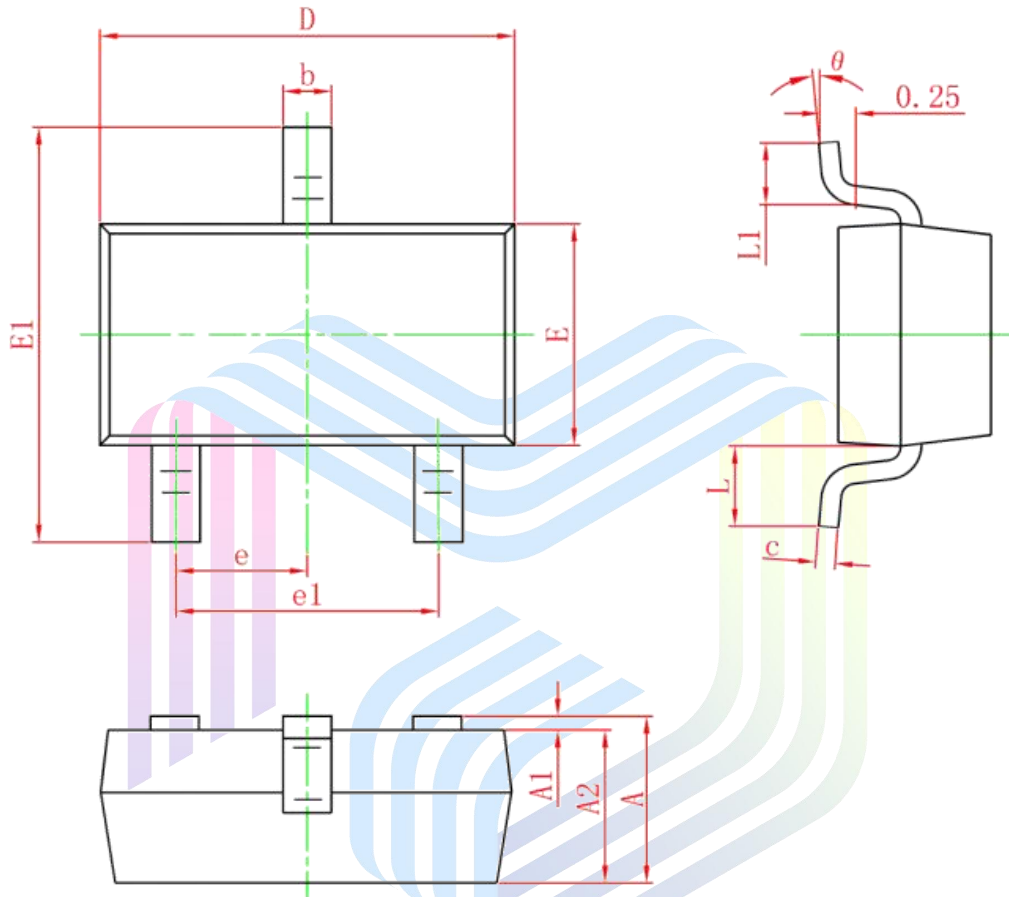
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 4.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .And device mounted on a large heatsink
- 5.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

## Typical Performance Characteristics



**Figure 7: Body Diode Characteristics**

**Figure 8: Threshold Voltage**



**Mechanical Dimensions:**
**SOT-23 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0	0.100	0	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.150	1.500	0.045	0.059
E1	2.250	2.650	0.089	0.104
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

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